



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10A105KA8NNNL

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 1µF, 25V, ±10%, X5R, 0603

A. Samsung Part Number

<u>CL</u> <u>10</u> <u>A</u> <u>105</u> <u>K</u> <u>A</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>L</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① S	Series	Samsung Multi-layer Ceramic Capacitor							
② S	Size	0603 (inch o	code)	L: 1.	6 ± 0.1	mm	W:	0.8 ± 0.1	mm
3 D	Dielectric	X5R		(8)	Inner	electrode	N	J i	
4 C	Capacitance	1 µF			Termii	nation	C	Cu	
⑤ C	Capacitance	±10 %			Plating	g	S	Sn 100%	(Pb Free)
to	olerance			9	Produ	ct	N	Vormal	
6 R	Rated Voltage	25 V		10	Specia	al	F	Reserved for	future use
⑦ T	Thickness	0.8 ± 0.1	mm	(1)	Packa	ging	C	Cardboard Ty	ype, 13" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition					
Capacitance	Within specified tolerance	1⊮±10% 1.0±0.2Vrms					
Tan δ (DF)	0.1 max.						
Insulation	10,000Mohm or 500Mohm- <i>μ</i> F	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	X5R						
Characterisitcs	(From -55 $^{\circ}$ to 85 $^{\circ}$, Capacitance change shoud be within ±15%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating : 80~120℃ for 10~30sec.)					
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition			
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours \times 3 direction (x, y, z)			
Moisture	Capacitance change : within ±12.5%	With rated voltage			
Resistance	Tan δ : 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR : 12.5№2-μF or Over				
High Temperature	Capacitance change : within ±12.5%	With 150% of the rated voltage			
Resistance	Tan δ: 0.125 max	Max. operating temperature			
	IR : 25MΩ·μF or Over				
		1000+48/-0hrs			
Temperature	Capacitance change : within ±7.5%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C			
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$			
		5 cycle test			

C. Recommended Soldering method:

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.